PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
YUSUKE OBA	03/18/2021
KENICHI YOSHIDA	02/25/2021
TAKASHI OHTSUKA	02/25/2021
YUICHIRO OKUYAMA	02/25/2021
TOMOYA HANAI	02/25/2021
YU FUKAE	02/25/2021

RECEIVING PARTY DATA

Name:	TDK CORPORATION
Street Address:	2-5-1, NIHONBASHI
Internal Address:	CHUO-KU
City:	TOKYO
State/Country:	JAPAN
Postal Code:	103-6128

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	17206656

CORRESPONDENCE DATA

Fax Number: (650)851-7232

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 6508517210
Email: alan@younglawfirm.com
Correspondent Name: YOUNG LAW FIRM, P.C. ALAN W. YOUNG
Address Line 1: 4370 ALPINE ROAD
Address Line 2: SUITE 202
Address Line 4: PORTOLA VALLEY, CALIFORNIA 94028

ATTORNEY DOCKET NUMBER:	WASH7329 (TDK20015US)
NAME OF SUBMITTER:	ALAN W YOUNG
SIGNATURE:	/alan w young/
DATE SIGNED:	03/19/2021

Total Attachments: 2

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ASSIGNMENT OF APPLICATION FOR PATENT

WHEREAS:

I, Yusuke OBA of Tokyo, JAPAN, I, Kenichi YOSHIDA of Tokyo, JAPAN, I, Takashi OHTSUKA of Tokyo, JAPAN, I, Yuichiro OKUYAMA of Tokyo, JAPAN, I, Tomoya HANAI of Tokyo, JAPAN and I, Yu FUKAE A of Tokyo, JAPAN (hereinafter referred to as ASSIGNOR(S)), have made a discovery or invention entitled:

ELECTRONIC COMPONENT AND MANUFACTURING METHOD THEREFOR

(Select One)

☒ for which application for Letters Patent of the United States has been executed on even date herewith,

☐ for which application for Letters Patent of the United States has been filed on ___________, under Application No.___________, and

WHEREAS:

TDK Corporation, a Japanese Corporation, having a place of business at 2-5-1, Nihonbashi, Chuo-ku, Tokyo 103-6128 JAPAN (hereinafter referred to as ASSIGNEE), is desirous of acquiring the entire interest in, to and under said invention and in, to and under Letters Patent or similar legal protection to be obtained therefor in the United States and in any and all foreign countries.

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN:

Be it known that for good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sells, assigns and transfers to ASSIGNEE, the full and exclusive right, title and interest to said discovery or invention in the United States and its territorial possessions and in all foreign countries and to all Letters Patent or similar legal protection in the United States and its territorial possessions and in any and all foreign countries to be obtained for said invention by said application or any continuation, division, renewal, substitute, reissue and/or any application claiming priority thereof, including any legal equivalent thereof, in a foreign country for the full term or terms for which the same may be granted.

I, SAID ASSIGNOR(S), hereby authorize and request the Commissioner of Patents and Trademarks of the United States of America and any Official of any country or countries foreign to the United States of America whose duty it is to issue Letters Patent on applications as aforesaid, to issue all such Letters Patent for said discovery or invention to the ASSIGNEE, as assignee of the entire right, title and interest in, to and under the same, for the sole use and benefit of the ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

I, SAID, ASSIGNOR(S), hereby covenant with ASSIGNEE, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned and that I have full right to convey the entire right, title and interest herein sold, assigned, transferred and set over;

AND I, SAID ASSIGNOR(S) hereby further covenant and agree that the ASSIGNEE, its successors, legal representatives, or assigns, may apply for foreign Letters Patent on said discovery or invention and claim the benefits of the International Convention, and that I will, at any time, when called upon to do so by the ASSIGNEE, its successors, legal representatives, or assigns, communicate to the ASSIGNEE, its successors, legal representatives, or assigns, as the case may be, any facts known to me respecting said discovery or invention, and execute and deliver any and all lawful papers that may be necessary or desirable to perfect the title to the said discovery or invention, the said applications and the said Letters Patent in the ASSIGNEE, its successors, legal representatives and assigns, and that if reissues of the said Letters Patent or disclaimers relating thereto, or divisions, continuations, or refilings of the said applications, or any thereof, shall hereafter be desired by the ASSIGNEE, its successors, legal representatives, or assigns, I will, at any time, when called upon to do so by the ASSIGNEE its successors, legal representatives, or assigns, sign all lawful papers, make all rightful oaths, execute and deliver all such disclaimers and all divisional, continuation and reissue applications so desired, and do all lawful acts requisite for the application for such reissues and the procuring thereof and for the filing of such disclaimers and such applications, and generally do everything possible to aid the ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention or discovery in all countries, all without further compensation but at the expense of the ASSIGNEE, its successors, legal representatives and assigns.

Inventor(s): Please Sign and Date Below:

(1) Yusuke Oba
Yusuke OBA
Date: Mar. 18. 2021

(2) Kenichi Yoshida
Kenichi YOSHIDA
Date: Feb. 25. 2021

(3) Takashi Ohtsuka
Takashi OHTSUKA
Date: Feb. 25. 2021

(4) Yuichiro Okuyama
Yuichiro OKUYAMA
Date: Feb. 25. 2021

(5) Tomoya Hanai
Tomoya HANAI
Date: Feb. 25, 2021

(6) Yu Fukae
Yu FUKAE
Date: Feb. 25. 2021

RECORDED: 03/19/2021

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